

# **SL28647**

# Clock Generator for Intel®CK505

#### **Features**

- **Compliant to Intel® CK505**
- **Selectable CPU frequencies**
- **Low power differential CPU clock pairs**
- **100-MHz low power differential SRC clocks**
- **96-MHz low power differential dot clock**
- **27-MHz Spread and Non-spread video clock**
- **48-MHz USB clock**
- **SRC clocks independently stoppable through CLKREQ#[1:9]**

#### **Table 1. Output Confguration Table**

- **100-MHz low power spreadable differential video clock**
- **33-MHz PCI clocks**
- **Buffered Reference Clock 14.318 MHz**
- **Low-voltage frequency select inputs**
- **I2C support with readback capabilities**
- **Ideal Lexmark Spread Spectrum profile for maximum electromagnetic interference (EMI) reduction**
- **3.3V power supply**
- **72-pin QFN package**







# **Pin Description**





## **Pin Description** (continued)



#### **Frequency Select Pins (FSA, FSB, and FSC)**

Host clock frequency selection is achieved by applying the appropriate logic levels to FSA, FSB, FSC inputs prior to CK PWRGD assertion (as seen by the clock synthesizer). Upon CK\_PWRGD being sampled HIGH by the clock chip (indicating processor CK\_PWRGD voltage is stable), the clock chip samples the FSA, FSB, and FSC input values. For all logic levels of FSA, FSB, and FSC, CK\_PWRGD employs a one-shot functionality in that once a valid HIGH on CK PWRGD has been sampled, all further CK PWRGD, FSA, FSB, and FSC transitions will be ignored, except in test mode.

#### **Serial Data Interface**

To enhance the flexibility and function of the clock synthesizer, a two-signal serial interface is provided. Through the Serial Data Interface, various device functions, such as individual clock output buffers, can be individually enabled or disabled. The registers associated with the Serial Data Interface initialize to their default setting upon power-up, and therefore use of this interface is optional. Clock device register changes are normally made upon system initialization, if any are required. The interface cannot be used during system operation for power management functions.



# **Data Protocol**

The clock driver serial protocol accepts byte write, byte read, block write, and block read operations from the controller. For block write/read operation, the bytes must be accessed in sequential order from lowest to highest byte (most significant bit first) with the ability to stop after any complete byte has been transferred. For byte write and byte read operations, the

#### **Table 2. Frequency Select Table FSA, FSB, and FSC**

system controller can access individually indexed bytes. The offset of the indexed byte is encoded in the command code, as described in *[Table 3](#page-3-0)*.

The block write and block read protocol is outlined in *[Table 4](#page-3-1)* while *[Table 5](#page-4-0)* outlines the corresponding byte write and byte read protocol. The slave receiver address is 11010010 (D2h)



#### <span id="page-3-0"></span>**Table 3. Command Code Definition**



#### <span id="page-3-1"></span>**Table 4. Block Read and Block Write Protocol**





# <span id="page-4-0"></span>**Table 5. Byte Read and Byte Write Protocol**



# **Control Registers**

# **Byte 0 Control Register 0**



## **Byte 1 Control Register 1**





# **Byte 2 Control Register 2**



# **Byte 3 Control Register 3**



## **Byte 4 Control Register 4**





# **Byte 4 Control Register 4** (continued)



## **Byte 5 Control Register 5**



# **Byte 6 Control Register 6**



# **Byte 7 Control Register 7**





# **Byte 7 Control Register 7** (continued)



#### **Byte 8 Vendor ID**



# **Byte 9 Control Register 9**



# **Byte 10 Control Register 10**





# **Byte 10 Control Register 10** (continued)



# **Byte 11 Control Register 11**



# **Byte 12 Control Register 12**





# **Byte 12 Control Register 12**



#### **Byte 13 Control Register 13**



# **Byte 14 Control Register 14**



# **Byte 15 Control Register 15**





# **Byte 15 Control Register 15**



## **Byte 16 Control Register 16**



# **Byte 17 Control Register 17**





#### **Byte 18 Control Register 18**



#### **Byte 19 Control Register 19**



#### **Table 6. Slew Rate Control Table**



#### **Table 7. Crystal Recommendation**



The SL28647 requires a Parallel Resonance Crystal. Substituting a series resonance crystal will cause the SL28647 to

operate at the wrong frequency and violate the ppm specification. For most applications there is a 300-ppm frequency



shift between series and parallel crystals due to incorrect loading.

## **Crystal Loading**

Crystal loading plays a critical role in achieving low ppm performance. To realize low ppm performance, the total capacitance the crystal will see must be considered to calculate the appropriate capacitive loading (CL).

*[Figure 1](#page-12-0)* shows a typical crystal configuration using the two trim capacitors. An important clarification for the following discussion is that the trim capacitors are in series with the crystal not parallel. It's a common misconception that load capacitors are in parallel with the crystal and should be approximately equal to the load capacitance of the crystal. This is not true.



**Figure 1. Crystal Capacitive Clarification**

#### <span id="page-12-0"></span>**Calculating Load Capacitors**

In addition to the standard external trim capacitors, trace capacitance and pin capacitance must also be considered to correctly calculate crystal loading. As mentioned previously, the capacitance on each side of the crystal is in series with the crystal. This means the total capacitance on each side of the crystal must be twice the specified crystal load capacitance (CL). While the capacitance on each side of the crystal is in series with the crystal, trim capacitors (Ce1,Ce2) should be calculated to provide equal capacitive loading on both sides.



**Figure 2. Crystal Loading Example**

Use the following formulas to calculate the trim capacitor

#### **Load Capacitance (each side)**

$$
Ce = 2 * CL - (Cs + Ci)
$$

#### **Total Capacitance (as seen by the crystal)**

$$
\text{CLe } = \frac{1}{\left(\frac{1}{\text{Ce1} + \text{Cs1} + \text{Ci1}} + \frac{1}{\text{Ce2} + \text{Cs2} + \text{Ci2}}\right)}
$$

CL..Crystal load capacitance CLe... Actual loading seen by crystal using standard value trim capacitors Ce... External trim capacitors



# **CLK\_REQ# Description**

values for Ce1 and Ce2.

The CLKREQ# signals are active LOW inputs used for clean enabling and disabling selected SRC outputs. The outputs controlled by CLKREQ# are determined by the settings in register byte 8. The CLKREQ# signal is a de-bounced signal in that it's state must remain unchanged during two consecutive rising edges of SRCC to be recognized as a valid assertion or deassertion. (The assertion and deassertion of this signal is absolutely asynchronous.)

#### **CLK\_REQ[1:9]# Assertion (CLKREQ# -> LOW)**

All differential outputs that were stopped are to resume normal operation in a glitch-free manner. The maximum latency from the assertion to active outputs is between 2 and 6 SRC clock periods (2 clocks are shown) with all SRC outputs resuming simultaneously. All stopped SRC outputs must be driven HIGH within 10 ns of CLKREQ# deassertion to a voltage greater than 200 mV.





**Figure 3. CLK\_REQ#[1:9] Deassertion/Assertion Waveform**

#### **CLK\_REQ[1:9]# Deassertion (CLKREQ# -> HIGH)**

The impact of deasserting the CLKREQ# pins is that all SRC outputs that are set in the control registers to stoppable via deassertion of CLKREQ# are to be stopped after their next transition. The final state of all stopped SRC clocks is Low/Low.

#### **PD (Power-down) Clarification**

The CK\_PWRGD/PD# pin is a dual-function pin. During initial power-up, the pin functions as CK\_PWRGD. Once CK PWRGD has been sampled HIGH by the clock chip, the pin assumes PD# functionality. The PD# pin is an asynchronous active LOW input used to shut off all clocks cleanly prior to shutting off power to the device. This signal is synchronized internal to the device prior to powering down the clock synthesizer. PD# is also an asynchronous input for powering up the system. When PD# is asserted LOW, all clocks need to be driven to a LOW value and held prior to turning off the VCOs and the crystal oscillator.

#### **PD (Power-down) Assertion**

When PD# is sampled LOW by two consecutive rising edges of CPUC, all single-ended outputs will be held LOW on their next HIGH-to-LOW transition and differential clocks must be held HIGH or tri-stated (depending on the state of the control register drive mode bit) on the next diff clock# HIGH-to-LOW transition within 4 clock periods. When the SMBus PD drive mode bit corresponding to the differential (CPU, SRC, and

DOT) clock output of interest is programmed to '0', the clock outputs are held with "Diff clock" pin driven HIGH, and "Diff clock#" tri-state. If the control register PD drive mode bit corresponding to the output of interest is programmed to "1", then both the "Diff clock" and the "Diff clock#" are tri-state. Note that *[Figure 4](#page-13-0)* shows CPUT = 133 MHz and PD drive mode = '1' for all differential outputs. This diagram and description is applicable to valid CPU frequencies 100, 133, 166, and 200 MHz. In the event that PD mode is desired as the initial power-on state, PD must be asserted HIGH in less than 10  $\mu$ s after asserting CK\_PWRGD. It should be noted that 96\_100\_SSC will follow the DOT waveform when selected for 96 MHz and the SRC waveform when in 100-MHz mode.

#### **PD Deassertion**

The power-up latency is less than 1.8 ms. This is the time from the deassertion of the PD pin or the ramping of the power supply until the time that stable clocks are output from the clock chip. All differential outputs stopped in a three-state condition resulting from power down will be driven high in less than 300  $\mu$ s of PD deassertion to a voltage greater than 200 mV. After the clock chip's internal PLL is powered up and locked, all outputs will be enabled within a few clock cycles of each other. *[Figure 5](#page-14-0)* is an example showing the relationship of clocks coming up. It should be noted that 96\_100\_SSC will follow the DOT waveform when selected for 96 MHz and the SRC waveform when in 100-MHz mode.

<span id="page-13-0"></span>





**Figure 5. Power-down Deassertion Timing Waveform**

#### <span id="page-14-0"></span>**CPU\_STP# Assertion**

The CPU\_STP# signal is an active LOW input used for synchronous stopping and starting the CPU output clocks while the rest of the clock generator continues to function. When the CPU\_STP# pin is asserted, all CPU outputs that are

set with the SMBus configuration to be stoppable via assertion of CPU\_STP# will be stopped within two–six CPU clock periods after being sampled by two rising edges of the internal CPUC clock. The final state of all stopped CPU clocks is High/Low when driven, Low/Low when tri-stated.



**Figure 7. CPU\_STP# Deassertion Waveform**



## **PCI\_STP# Assertion**

The PCI STP# signal is an active LOW input used for synchronous stopping and starting the PCI outputs and SRC outputs if they are set to be stoppable in SMbus while the rest of the clock generator continues to function. The set-up time for capturing PCI\_STP# going LOW is 10 ns  $(t_{\text{SU}})$ . (See *[Figure 9](#page-15-0)*.) The PCIF clocks will not be affected by this pin if their corresponding control bit in the SMBus register is set to allow them to be free running. All stopped PCI outputs are

driven Low, SRC outputs are High/Low if set to driven and Low/Low if set to tri-state.

#### **PCI\_STP# Deassertion**

The deassertion of the PCI\_STP# signal will cause all PCI and stoppable PCIF clocks to resume running in a synchronous manner within two PCI clock periods after PCI\_STP# transitions to a HIGH level.

<span id="page-15-0"></span>



**SL28647**





#### **Table 8. Default Condition for Output Driver Status**



### **Table 9. Default Condition for Output Driver Status**







**Figure 13. SL28647 State Diagram**



<span id="page-17-0"></span>**Figure 14. BSEL Serial Latching**



# **Absolute Maximum Conditions**



**Multiple Supplies:** The Voltage on any input or I/O pin cannot exceed the power pin during power-up. Power supply sequencing is NOT required.

# **DC Electrical Specifications**



# **AC Electrical Specifications**



















#### **Test and Measurement Set-up**

#### **For Single-ended Signals and Reference**

The following diagram shows test load configurations for the single-ended PCI, USB, and REF output signals.



#### **Figure 15.Single-ended Load Configuration Low Drive Option**

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**Figure 16. Single-ended Load Configuration High Drive Option**

The following diagram shows the test load configuration for the differential CPU and SRC outputs.



**Figure 17. 0.8V Differential Load** 



**Figure 18. Single-ended Output Signals (for AC Parameters Measurement)**



# **Ordering Information**



This device is Pb free and RoHS compliant. Parts supporting extended temperature is available upon request.



# **Package Diagram**



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# **Document History Page**

